- Designed for TDMA IS-54 Receiver IF Applications
- Low Insertion Loss
- Hermetic 13.3 X 6.5 mm Surface-mount Case
- Unbalanced Input and Output
- Complies with Directive 2002/95/EC (RoHS)


## Absolute Maximum Ratings

| Rating | Value | Units |
| :--- | :---: | :---: |
| Maximum Incident Power in Passband | +10 | dBm |
| Maximum DC Voltage Between any 2 terminals | 30 | VDC |
| Storage Temperature Range | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Suitable for Lead-free Soldering - Maximum Soldering Profile | $260^{\circ} \mathrm{C}$ for 30 s |  |



SM13365-12

Electrical Characteristics

| Characteristic | Sym | Notes | Min | Typ | Max | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Nominal Center Frequency | $\mathrm{f}_{\mathrm{C}}$ | 1 | 86.850 |  |  | MHz |
| Passband Insertion Loss at fc | IL |  |  | 3 | 4.0 | dB |
| 3 dB Passband <br> Amplitude Ripple over fc $\pm 15 \mathrm{kHz}$ Group Delay Variation over fc $\pm 10 \mathrm{kHz}$ | $\mathrm{BW}_{3}$ | 1, 2 | $\pm 12$ | $\pm 25$ |  | kHz |
|  |  |  |  |  | 1.0 | $\mathrm{dB}_{\mathrm{P}-\mathrm{P}}$ |
|  | GDV |  |  |  | 6.0 | $\mu \mathrm{SP}_{\text {P-P }}$ |
| Third-Order Intermod. for -20 dBm tones at fc $\pm 60$ \& 120 kHz |  |  |  |  | -95 | dBm |
| Rejection fc $\pm 60 \mathrm{kHz}$ |  | 1, 2, 3 | 11 | 16 |  | dB |
| fc -880 kHz to fc -940 kHz <br> Ultimate |  |  | 65 |  |  |  |
|  |  |  |  | 65 |  |  |
| Operating Temperature Range | TA | 1 | -20 |  | +70 | ${ }^{\circ} \mathrm{C}$ |


| Impedance Matching to $50 \Omega$ unbalanced | External L-C |
| :--- | :---: |
| Case Style | SM13365-12 $13.3 \times 6.5 \mathrm{~mm}$ Nominal Footprint |
| Lid Symbolization (YY=year, WW=week) See note 4 | RFM PX1002 YYWW |
| Standard 7" Reel Quantity | 500 units |
| Standard 13" Reel Quantity | 1000 units |

## Electrical Connections

| Connection | Terminals |
| :--- | :---: |
| Port 1Hot | 2 |
| Port 1 Gnd Return | 3 |
| Port 2 Hot | 8 |
| Port 2 Gnd Return | 9 |
| Case Ground | All Others |

## Caution: Electrostatic Sensitive Device. Observe precautions for handling.

## NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to $50 \Omega$ and measured with $50 \Omega$ network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and
"ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Either Port 1 or Port 2 may be used for either input or output in the design.

However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

## SCHEMATIC, PX1øø2 (DEMO)





## Tape and Reel Specifications



| "B" |  | Quantity Per Reel |
| :---: | :---: | :---: |
| Inches | millimeters |  |
| 7 | 178 | 500 |
| 13 | 330 | 3000 |



## COMPONENT ORIENTATION and DIMENSIONS



| Carrier Tape Dimensions |  |
| :---: | :---: |
| Ao | 7.0 mm |
| Bo | 13.8 mm |
| Ko | 2.0 mm |
| Pitch | 12.0 mm |
| W | 24.0 mm |



## SM13365-12 Case

## 12-Terminal Ceramic Surface-Mount Case $13.3 \times 6.5$ mm Nominal Footprint



| Case Dimensions |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Dimension | mm |  |  | Inches |  |  |
|  | Min | Nom | Max | Min | Nom | Max |
| A | 13.08 | 13.31 | 13.60 | 0.515 | 0.524 | 0.535 |
| B | 6.27 | 6.50 | 6.80 | 0.247 | 0.256 | 0.268 |
| C |  | 1.91 | 2.00 |  | 0.075 | 0.079 |
| D |  | 1.50 |  |  | 0.059 |  |
| E |  | 0.79 |  |  | 0.031 |  |
| H |  | 1.0 |  |  | 0.039 |  |
| P |  | 2.54 |  |  | 0.100 |  |


| Materials |  |
| :---: | :---: |
| Solder Pad <br> Plating | 0.3 to $1.0 \mu \mathrm{~m}$ Gold over 1.27 to $8.89 \mu \mathrm{~m}$ Nickel |
| Lid Plating | 2.0 to $3.0 \mu \mathrm{~m}$ Nickel |
| Body | $\mathrm{Al}_{2} \mathrm{O}_{3}$ Ceramic |
| Pb Free |  |



